



**16MByte (16M x 9) DRAM Module - 16Mx1 based
30-pin SIMM**

Features

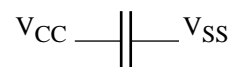
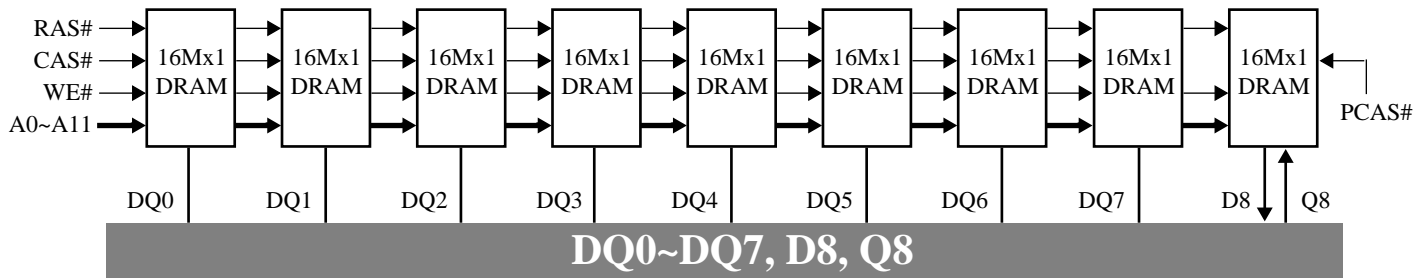
- Standard : JEDEC
- Configuration : Parity
- Access Time : 60/70/80ns
- Operation Mode : FPM
- Operating Voltage : 3.3/5.0V
- Refresh : 4K
- Device Physicals : 300mil SOJ/TSOP
- Lead Finish : Gold/Solder
- Length x Height : 3.500" x 0.830"
- No. of sides : Double-sided

Part Numbers

- SM509161004PUUU : FPM, 5.0V
- SM509161014PUUU : FPM, 3.3V

Note: Refer last page for all "U" options.

Functional Diagram



Decoupling capacitors
to all devices.

(All specifications of this device are subject to change without notice.)



Pin Name

A0~A11 Addresses
DQ0~DQ7 Data Inputs/Outputs
D8 Parity Data In
Q8 Parity Data Out
PCAS# Parity CAS
CAS# Column Address Strobe
RAS# Row Address Strobe
WE# Write Enable
V_{CC} Power Supply
V_{SS} Ground
NC No Connection

Pin No.	Pin Designation	Pin No.	Pin Designation
1	V _{CC}	16	DQ4
2	CAS#	17	A8
3	DQ0	18	A9
4	A0	19	A10
5	A1	20	DQ5
6	DQ1	21	WE#
7	A2	22	V _{SS}
8	A3	23	DQ6
9	V _{SS}	24	A11
10	DQ2	25	DQ7
11	A4	26	Q8
12	A5	27	RAS#
13	DQ3	28	PCAS#
14	A6	29	D8
15	A7	30	V _{CC}



DC Characteristics

Absolute Maximum Ratings

Parameter	Symbol	Ratings		Unit
		V _{CC} =3.3V	V _{CC} =5.0V	
Voltage on any pin relative to V _{SS}	V _T	- 0.5 to +4.6	- 1.0 to +7.0	V
Power Dissipation	P _T	9	9	W
Operating Temperature	T _{opr}	0 to +70	0 to +70	°C
Storage Temperature	T _{stg}	- 55 to +150	- 55 to +150	°C
Short Circuit Output Current	I _{OS}	50	50	mA

Recommended DC Operating Conditions

(T_A = 0 to +70°C)

Parameter	Symbol	V _{CC} =3.3V			V _{CC} =5.0V			Unit
		Min	Typ	Max	Min	Typ	Max	
Supply Voltage	V _{CC}	3.0	3.3	3.6	4.5	5.0	5.5	V
Ground	V _{SS}	0	0	0	0	0	0	V
Input High Voltage	V _{IH}	2.0	-	V _{CC} +0.3	2.4	-	V _{CC} +1.0	V
Input Low Voltage	V _{IL}	-0.3	-	0.8	-1.0	-	0.8	V

Capacitance

(V_{CC} = 3.3V±10%/5.0V±10%, T_A = +25°C)

Parameter	Symbol	Max	Unit
Input Capacitance (Address)	C _{I1}	55	pF
Input Capacitance (RAS#, WE#)	C _{I2}	73	pF
Input Capacitance (CAS#)	C _{I3}	66	pF
Input Capacitance (PCAS#)	C _{I4}	17	pF
Input Capacitance (D8)	C _{I5}	17	pF
Output Capacitance (Q8)	C _{O1}	17	pF
Input/Output Capacitance (DQ0~DQ7)	C _{I/O}	17	pF

Notes : Capacitance is sampled per Mil-Std-883.



DC Characteristics (cont'd)

($V_{CC} = 3.3V \pm 10\%$, $V_{SS} = 0V$, $T_A = 0$ to $+70$ °C)

Parameter	Symbol	Test Conditions	60ns		70ns		80ns		Unit
			Min	Max	Min	Max	Min	Max	
Input Leakage Current	I_{LI}	$0V \leq V_{in} \leq V_{CC} + 0.3V$	-90	90	-90	90	-90	90	μA
Output Leakage Current	I_{LO}	$0V \leq V_{out} \leq V_{CC}$ $D_{out} = \text{Disable}$	-10	10	-10	10	-10	10	μA
Output High Voltage	V_{OH}	High $I_{out} = -2mA$	2.4	-	2.4	-	2.4	-	V
Output Low Voltage	V_{OL}	Low $I_{out} = 2mA$	-	0.4	-	0.4	-	0.4	V

($V_{CC} = 5.0V \pm 10\%$, $V_{SS} = 0V$, $T_A = 0$ to $+70$ °C)

Parameter	Symbol	Test Conditions	60ns		70ns		80ns		Unit
			Min	Max	Min	Max	Min	Max	
Input Leakage Current	I_{LI}	$0V \leq V_{in} \leq V_{CC} + 0.5V$	-90	90	-90	90	-90	90	μA
Output Leakage Current	I_{LO}	$0V \leq V_{out} \leq V_{CC}$ $D_{out} = \text{Disable}$	-10	10	-10	10	-10	10	μA
Output High Voltage	V_{OH}	High $I_{out} = -5mA$	2.4	-	2.4	-	2.4	-	V
Output Low Voltage	V_{OL}	Low $I_{out} = 4.2mA$	-	0.4	-	0.4	-	0.4	V



DC Characteristics (cont'd)

($V_{CC} = 3.3V \pm 10\%$, $V_{SS} = 0V$, $T_A = 0$ to $+70$ °C)

Parameter	Symbol	Test Conditions	Max.			Unit	Note
			60ns	70ns	80ns		
Operating Current	I_{CC1}	RAS#, CAS# cycling; $t_{RC} = \text{min.}$	720	630	540	mA	1, 2
Standby Current	I_{CC2}	LVTTL Interface RAS#, CAS# $\geq V_{IH}$ $D_{out} = \text{High-Z}$	18	18	18	mA	
		CMOS Interface RAS#, CAS# $\geq V_{CC} - 0.2V$ $D_{out} = \text{High-Z}$	9	9	9	mA	
RAS#-only Refresh Current	I_{CC3}	CAS#=VIH; RAS#, Address cycling @ $t_{RC}=\text{min.}$	720	630	540	mA	2
CAS#-before-RAS# Refresh Current	I_{CC4}	RAS#, CAS# cycling @ $t_{RC}=\text{min.}$	720	630	540	mA	
Fast Page Mode Current	I_{CC5}	RAS#=VIL, CAS#, Address cycling @ $t_{PC}=\text{min.}$	630	540	450	mA	1, 3

($V_{CC} = 5.0V \pm 10\%$, $V_{SS} = 0V$, $T_A = 0$ to $+70$ °C)

Parameter	Symbol	Test Conditions	Max.			Unit	Note
			60ns	70ns	80ns		
Operating Current	I_{CC1}	RAS#, CAS# cycling; $t_{RC} = \text{min.}$	720	630	540	mA	1, 2
Standby Current	I_{CC2}	TTL Interface RAS#, CAS# $\geq V_{IH}$ $D_{out} = \text{High-Z}$	18	18	18	mA	
		CMOS Interface RAS#, CAS# $\geq V_{CC} - 0.2V$ $D_{out} = \text{High-Z}$	9	9	9	mA	
RAS#-only Refresh Current	I_{CC3}	CAS#=VIH; RAS#, Address cycling @ $t_{RC}=\text{min.}$	720	630	540	mA	2
CAS#-before-RAS# Refresh Current	I_{CC4}	RAS#, CAS# cycling @ $t_{RC}=\text{min.}$	720	630	540	mA	
Fast Page Mode Current	I_{CC5}	RAS#=VIL, CAS#, Address cycling @ $t_{PC}=\text{min.}$	630	540	450	mA	1, 3

- Notes: 1. Values depend on output load condition when the device is selected. Maximum values are specified at the output open condition.
 2. Address can be changed once or less while RAS# = V_{IL} .
 3. Address can be changed once or less while CAS# = V_{IH} .

AC Characteristics

($V_{CC} = 3.3V \pm 10\% / 5.0V \pm 10\%$, $V_{SS} = 0V$, $T_A = 0$ to $+70$ °C)

Parameter	Symbol	60ns		70ns		80ns		Unit	Notes
		Min	Max	Min	Max	Min	Max		
<u>Common to Read and Write Cycles</u>									
Column address set-up time	t_{ASC}	0	-	0	-	0	-	ns	
Row address set-up time	t_{ASR}	0	-	0	-	0	-	ns	
Column address hold time	t_{CAH}	10	-	15	-	15	-	ns	
CAS# pulse width	t_{CAS}	15	10000	18	10000	20	10000	ns	
CAS# to output in Low-Z	t_{CLZ}	0	-	0	-	0	-	ns	3
CAS# to RAS# precharge time	t_{CRP}	5	-	5	-	5	-	ns	
CAS# hold time	t_{CSH}	60	-	70	-	80	-	ns	
RAS# to column address delay time	t_{RAD}	15	30	15	35	15	40	ns	10
Row address hold time	t_{RAH}	10	-	10	-	10	-	ns	
RAS# pulse width	t_{RAS}	60	10000	70	10000	80	10000	ns	
Random read/write cycle time	t_{RC}	110	-	130	-	150	-	ns	
RAS# to CAS# delay time	t_{RCD}	20	40	20	50	20	60	ns	4
RAS# precharge time	t_{RP}	40	-	50	-	60	-	ns	
RAS# hold time	t_{RSH}	15	-	18	-	20	-	ns	
Transition time (rise and fall)	t_T	3	50	3	50	3	50	ns	2
<u>Read Cycle</u>									
Access time from column address	t_{AA}	-	30	-	35	-	40	ns	3, 10
Access time from CAS#	t_{CAC}	-	15	-	18	-	20	ns	3, 4, 5
Output buffer turn-off delay	t_{OFF}	0	15	0	15	0	15	ns	6
Access time from RAS#	t_{RAC}	-	60	-	70	-	80	ns	3, 4
Column address to RAS# lead time	t_{RAL}	30	-	35	-	40	-	ns	
Read command hold time referenced to CAS#	t_{RCH}	0	-	0	-	0	-	ns	8
Read command set-up time	t_{RCS}	0	-	0	-	0	-	ns	
Read command hold time referenced to RAS#	t_{RRH}	0	-	0	-	0	-	ns	8
<u>Write Cycle</u>									
Write command to CAS# lead time	t_{CWL}	15	-	15	-	20	-	ns	
Data-in hold time	t_{DH}	10	-	15	-	15	-	ns	9
Data-in set-up time	t_{DS}	0	-	0	-	0	-	ns	9
Write command to RAS# lead time	t_{RWL}	20	-	20	-	25	-	ns	
Write command hold time	t_{WCH}	10	-	10	-	15	-	ns	
Write command set-up time	t_{WCS}	0	-	0	-	0	-	ns	7
Write command pulse width	t_{WP}	10	-	10	-	15	-	ns	



AC Characteristics (cont'd)

($V_{CC} = 3.3V \pm 10\% / 5.0V \pm 10\%$, $V_{SS} = 0V$, $T_A = 0$ to $+70$ °C)

Parameter	Symbol	60ns		70ns		80ns		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Fast page Mode Cycle									
Access time from CAS# precharge	t_{ACP}	-	35	-	40	-	45	ns	3, 11
CAS# precharge time	t_{CP}	10	-	10	-	10	-	ns	
Fast page mode cycle time	t_{PC}	40	-	45	-	50	-	ns	
RAS# pulse width	t_{RASP}	60	200000	70	200000	80	200000	ns	12
RAS# hold time from CAS# precharge	t_{RHCP}	35	-	40	-	45	-	ns	
Refresh Cycle									
CAS# hold time (CBR refresh)	t_{CHR}	10	-	15	-	15	-	ns	1
CAS# set-up time (CBR refresh)	t_{CSR}	5	-	5	-	5	-	ns	1
Refresh period	t_{REF}								
4K refresh		-	64	-	64	-	64	ms	
RAS# precharge to CAS# hold time	t_{RPC}	5	-	5	-	5	-	ns	

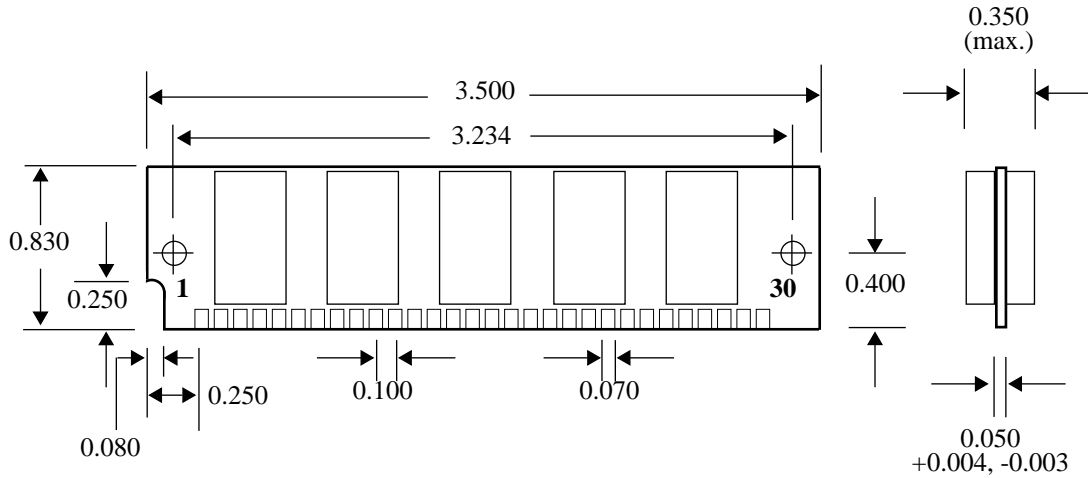
- Notes:**
1. An initial pause of at least 200 μ s is required after power-up followed by any eight RAS# cycles before device operation is achieved.
 2. $V_{IH}(\text{min})$ and $V_{IL}(\text{max})$ are reference levels for measuring timing of input signals. Transition times are measured between $V_{IH}(\text{min})$ and $V_{IL}(\text{max})$ and are assumed to be 5ns for all inputs.
 3. Measure with a load equivalent to 2 TTL(5V device)/1 TTL(3.3V device) loads and 100pF.
 4. Operation within the $t_{RCD}(\text{max})$ limit ensures that $t_{RAC}(\text{max})$ limit can be met; $t_{RCD}(\text{max})$ is specified as a reference point only. If t_{RCD} is greater than the specified $t_{RCD}(\text{max})$ limit, then access time is controlled exclusively by t_{CAC} .
 5. Assumes that $t_{RCD} \geq t_{RCD}(\text{max})$.
 6. This parameter defines the time at which the output achieves open circuit condition and is not referenced to V_{OH} or V_{OL} .
 7. t_{WCS} is non restrictive operating parameter. It is included in the data sheet as electrical characteristic only. If $t_{WCS} \geq t_{WCS}(\text{min})$ the cycle is an early write cycle and the data out pin will remain at high impedance for the duration of the cycle.
 8. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
 9. These parameters are referenced to the CAS# leading edge in early write cycles.
 10. Operation within the $t_{RAD}(\text{max})$ limit ensures that $t_{RAC}(\text{max})$ can be met. $t_{RAD}(\text{max})$ is specified as a reference point only. If t_{RAD} is greater than the specified $t_{RAD}(\text{max})$ limit, then access time is controlled by t_{AA} .
 11. Access time is determined by the longer of t_{AA} , t_{CAC} or t_{ACP} .
 12. t_{RASP} defines RAS# pulse width in fast page mode cycles.
 13. t_{AR} , t_{WC} , t_{DHR} are referenced to $t_{RAD}(\text{max})$.



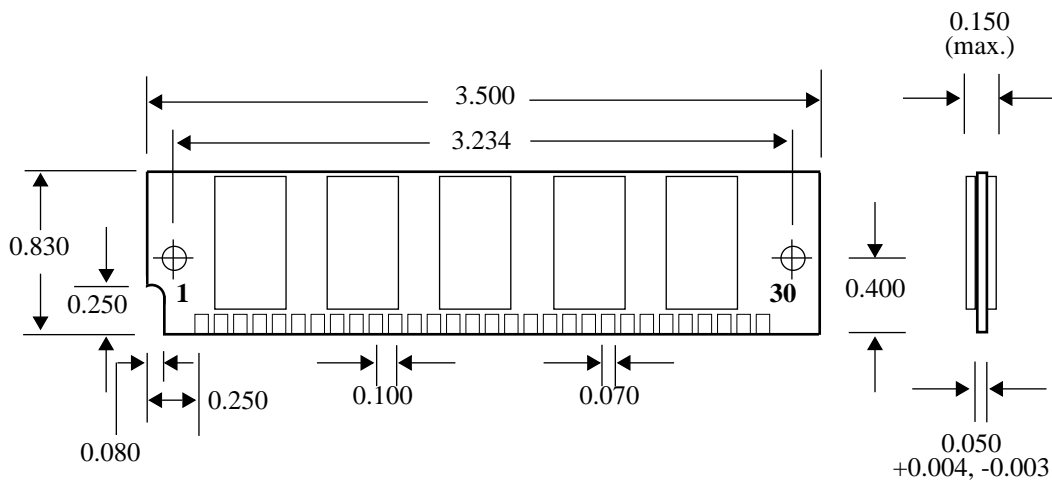
Physical Dimensions

30-pin SIMM Module

SOJ Based



TSOP Based

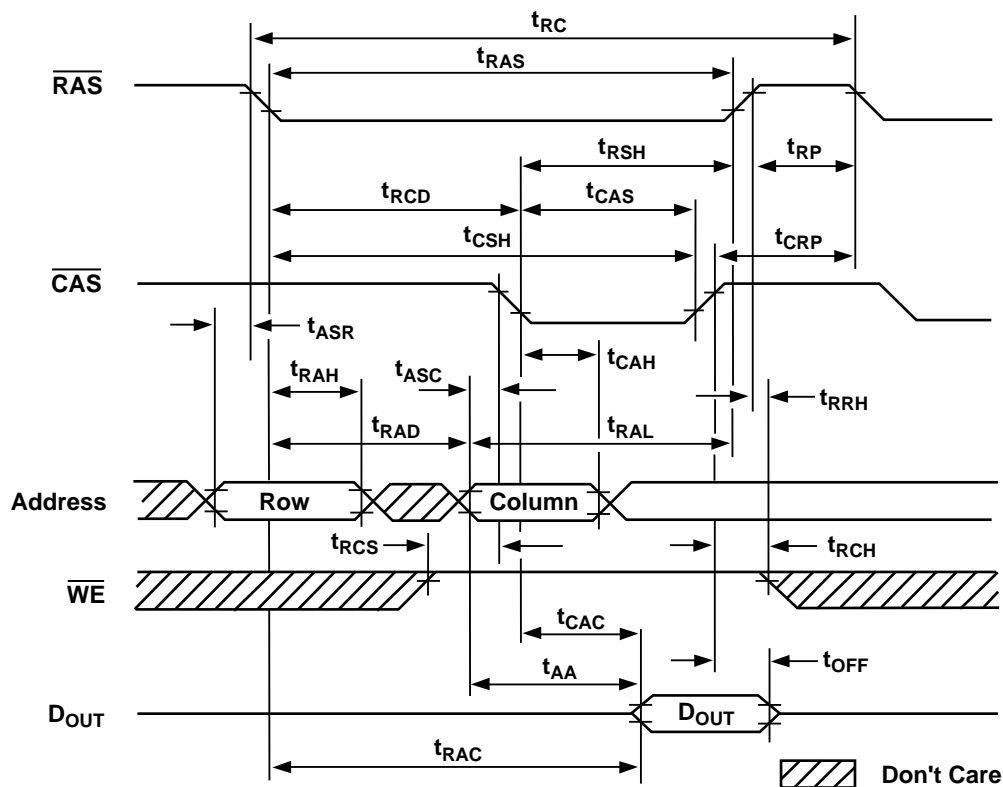


(All dimensions are in inches with ± 0.005 " tolerance unless specified otherwise.)



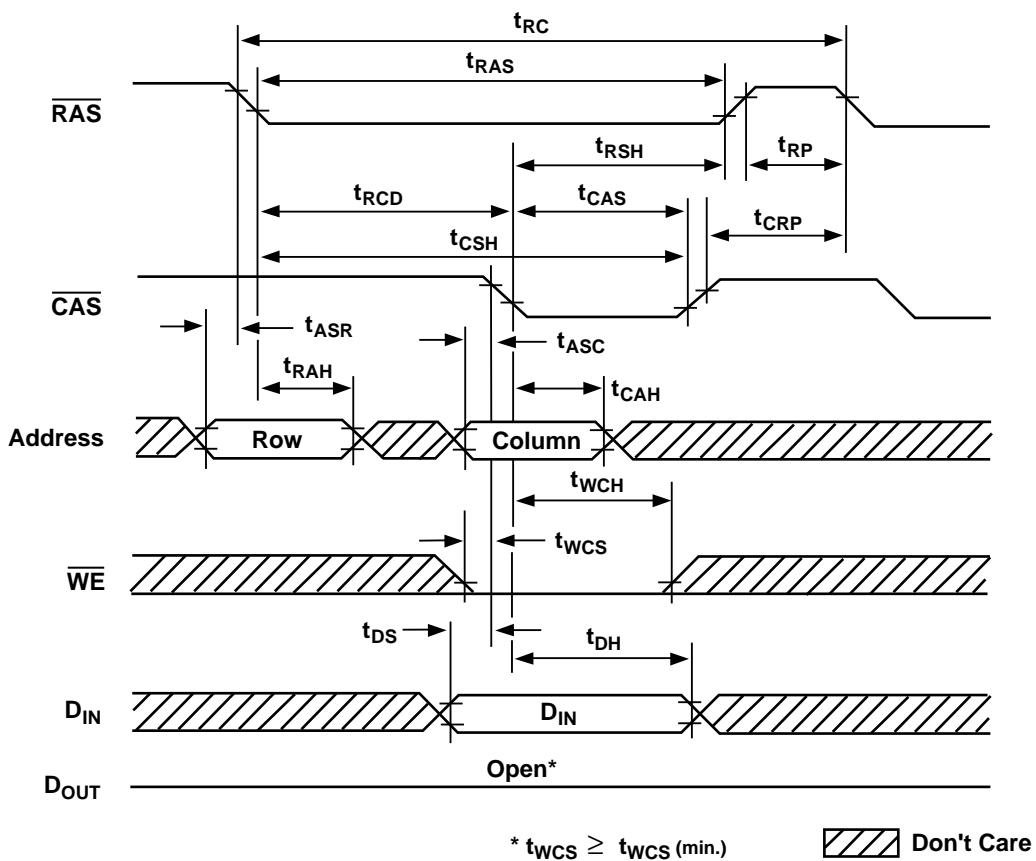
Timing Waveforms

Read Cycle



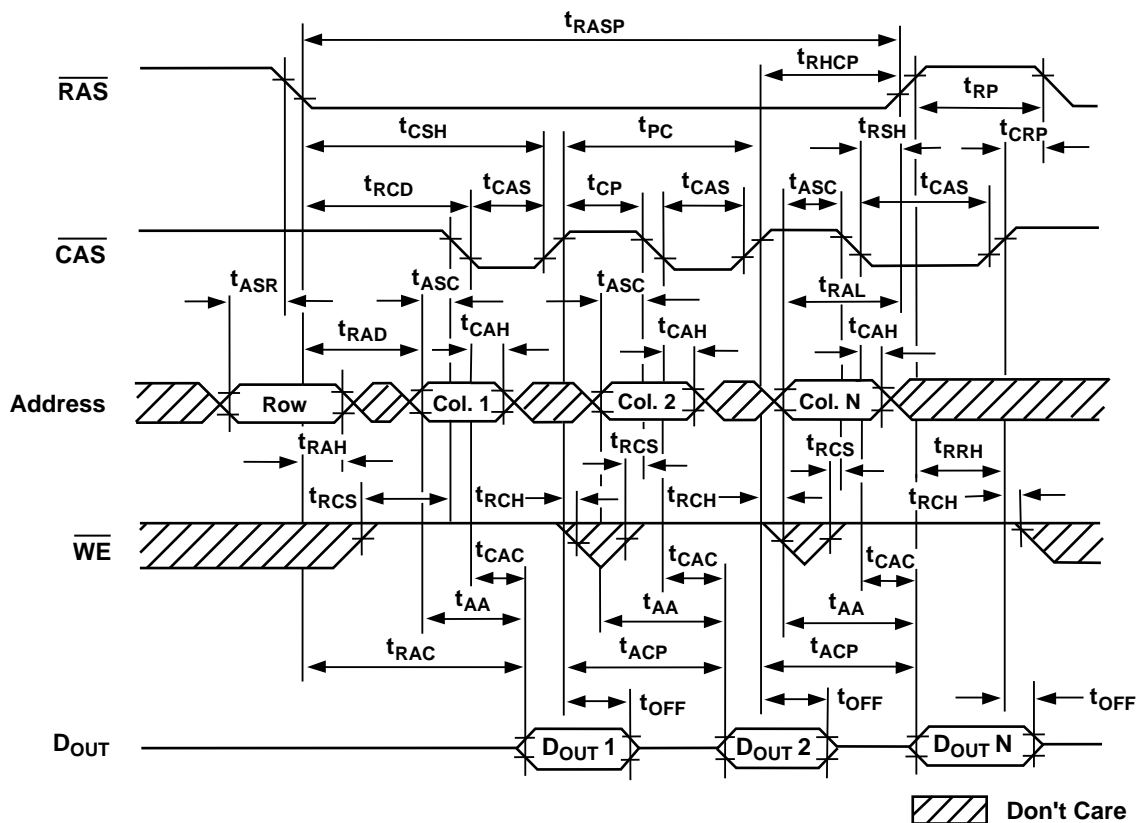


Write Cycle (Early Write)



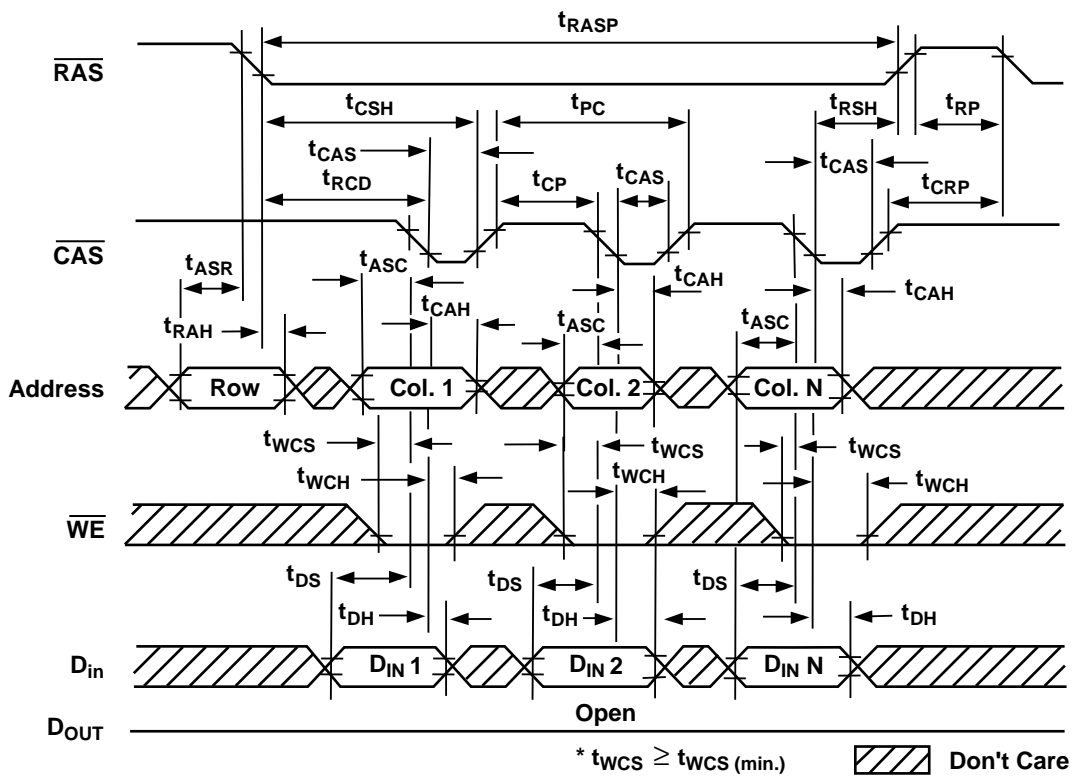


Fast Page Mode Read Cycle



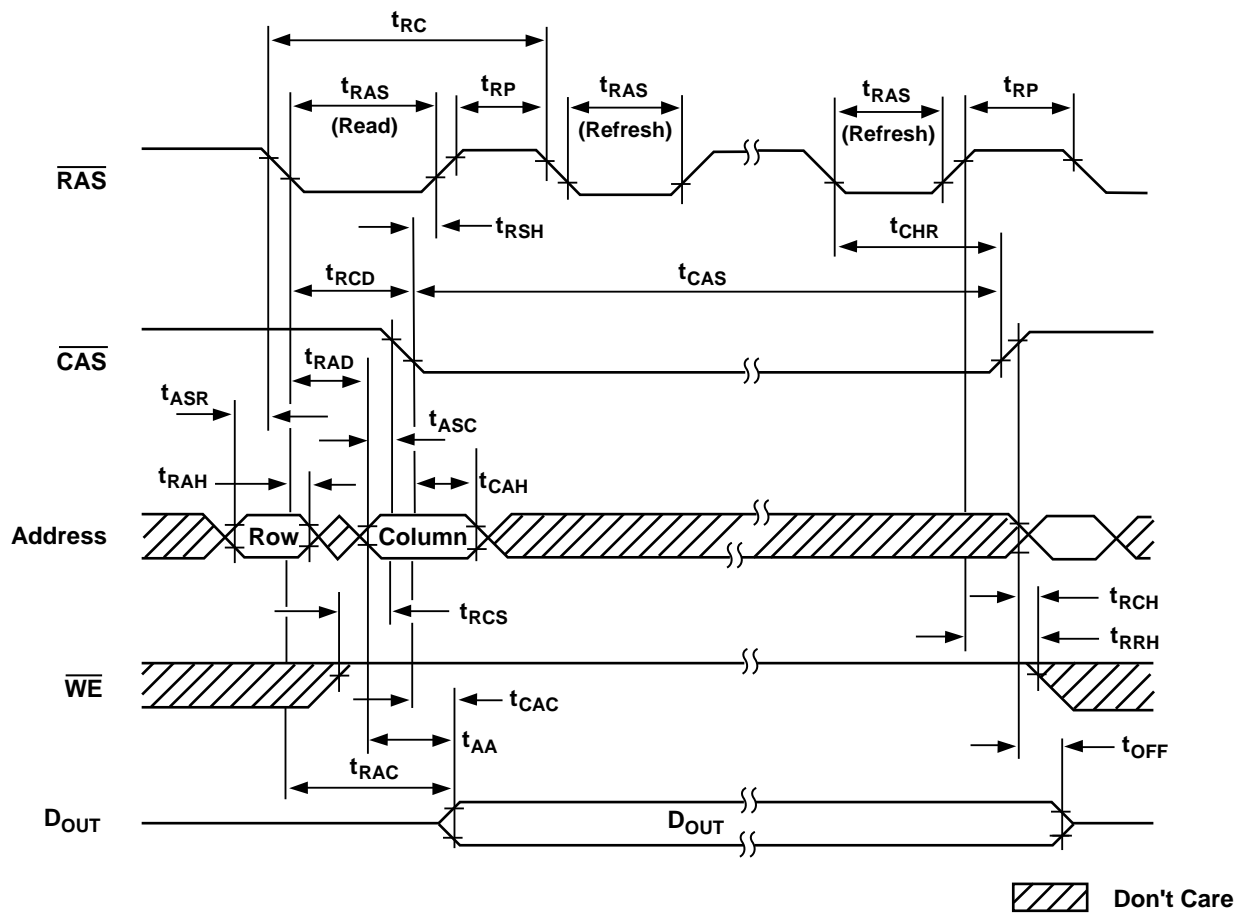


Fast Page Mode Write Cycle (Early Write)



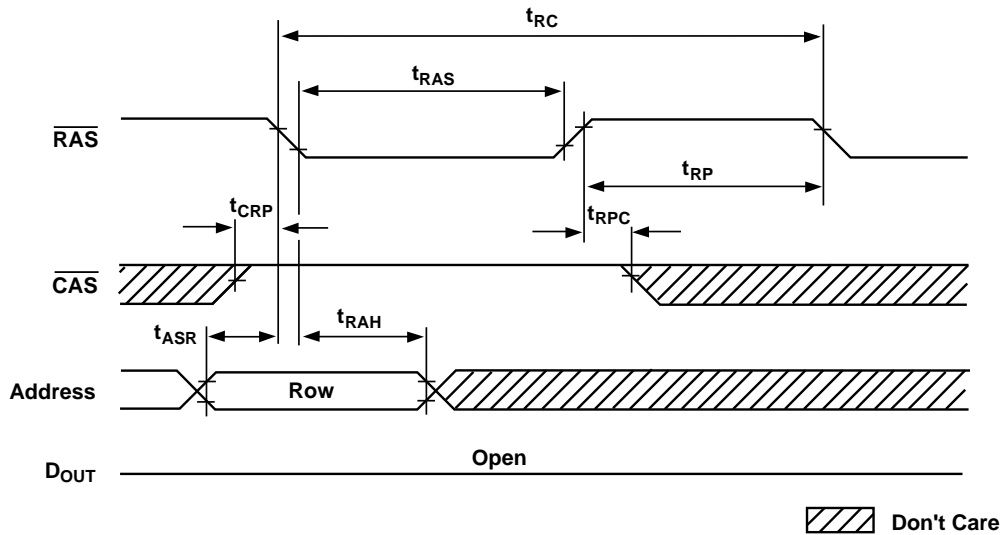


Hidden Refresh Cycle

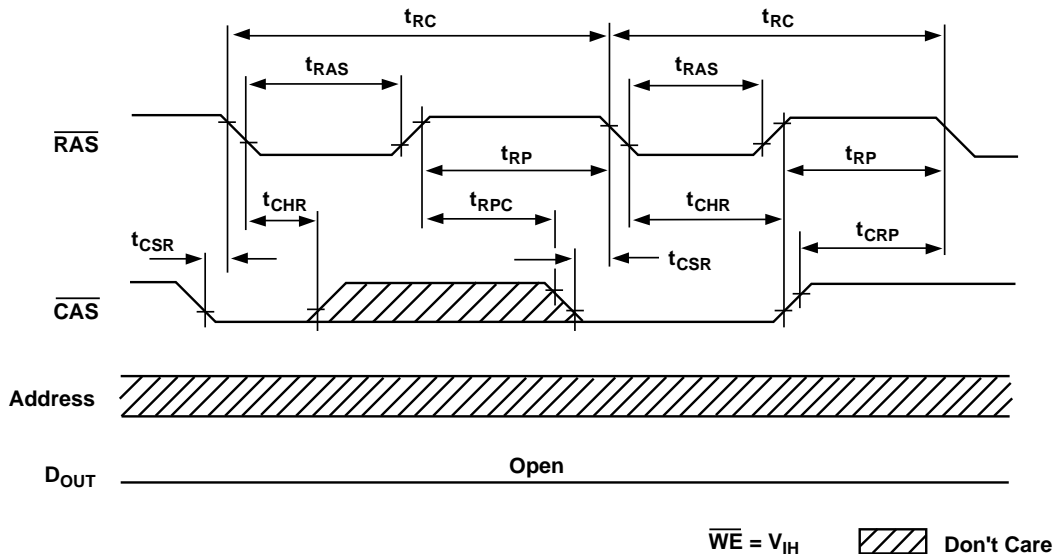




RAS# Only Refresh Cycle



CAS#-Before-RAS# Refresh Cycle





Ordering Information

SM 5 09 16 1 0 U 4 P U U U
 (1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12)

- (1) **SMART Modular Technologies**
- (2) **Product Category**
5 : DRAM SIMM / DIMM
- (3) **Module Data Bus Width**
09 : x9
- (4) **Module Address Depth**
16 : 16M
- (5) **Device Data Width**
1 : x1
- (6) **Special Device Feature**
0 : Standard
- (7) **Voltage / Mode**
0 : 5.0V / Fast Page Mode
1 : 3.3V / Fast Page Mode
- (8) **Refresh / Power**
4 : 4K Ref. / Standard Power
- (9) **Module Configuration**
P : Parity
- (10) **Device Physicals**
3 : SOJ DRAMs (300mil)
5 : TSOP DRAMs (300mil)
- (11) **Module Lead Finish**
S : Solder
G : Gold
- (12) **Module Access Speed**
6 : 60ns
7 : 70ns
8 : 80ns

Note : "U" in the part number should be replaced by user specified option.



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